

December 2007

74ABT244 Octal Buffer/Line Driver with 3-STATE Outputs

Features

- Non-inverting buffers
- Output sink capability of 64mA, source capability of 32mA
- Guaranteed output skew
- Guaranteed multiple output switching specifications
- Output switching specified for both 50pF and 250pF loads
- Guaranteed simultaneous switching, noise level and dynamic threshold performance
- Guaranteed latchup protection
- High-impedance, glitch-free bus loading during entire power up and power down cycle
- Nondestructive, hot-insertion capability
- Disable time less than enable time to avoid bus contention

General Description

The ABT244 is an octal buffer and line driver with 3-STATE outputs designed to be employed as a memory and address driver, clock driver, or bus-oriented transmitter/receiver.

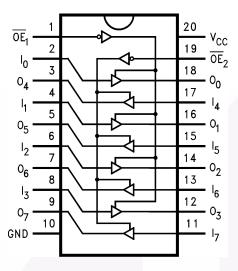
Ordering Information

Order Number	Package Number	Package Description
74ABT244CSC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74ABT244CSJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ABT244CMSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
74ABT244CMTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagram



Pin Descriptions

Pin Names	Description
\overline{OE}_1 , \overline{OE}_2	Output Enable Input (Active LOW)
I ₀ –I ₇	Inputs
O ₀ -O ₇	Outputs

Truth Table

OE ₁	I ₀₋₃	O ₀₋₃	OE ₂	I ₄₋₇	O ₄₋₇
Н	Х	Z	Н	Х	Z
L	Н	Н	L	Н	Н
L	L	L	L	L	L

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
T _{STG}	Storage Temperature	−65°C to +150°C
T _A	Ambient Temperature Under Bias	−55°C to +125°C
T _J	Junction Temperature Under Bias	−55°C to +150°C
V _{CC}	V _{CC} Pin Potential to Ground Pin	-0.5V to +7.0V
V _{IN}	Input Voltage ⁽¹⁾	-0.5V to +7.0V
I _{IN}	Input Current ⁽¹⁾	-30mA to +5.0mA
V _O	Voltage Applied to Any Output	
	Disabled or Power-Off State	-0.5V to 5.5V
	HIGH State	–0.5V to V _{CC}
	Current Applied to Output in LOW State (Max.)	twice the rated I _{OL} (mA)
	DC Latchup Source Current	-500mA
	Over Voltage Latchup (I/O)	10V

Note:

1. Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
T _A	Free Air Ambient Temperature	-40°C to +85°C
V _{CC}	Supply Voltage	+4.5V to +5.5V
ΔV / Δt	Minimum Input Edge Rate	
	Data Input	50mV/ns
	Enable Input	20mV/ns

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DC Electrical Characteristics

Symbol	P	arameter	V _{CC}	Conditions	Min.	Тур.	Max.	Units
V _{IH}	Input HIGH	Voltage		Recognized HIGH Signal	2.0			V
V _{IL}	Input LOW	Voltage		Recognized LOW Signal			0.8	V
V _{CD}	Input Clam	p Diode Voltage	Min.	I _{IN} = -18mA			-1.2	V
V _{OH}	Output HIG	H Voltage	Min.	$I_{OH} = -3mA$	2.5			V
				$I_{OH} = -32mA$	2.0			
V _{OL}	Output LOV	V Voltage		I _{OL} = 64mA			0.55	V
I _{IH}	Input HIGH	Current	Max.	$V_{IN} = 2.7V^{(3)}$			1	μA
				$V_{IN} = V_{CC}$			1	
I _{BVI}	Input HIGH Breakdown		Max.	V _{IN} = 7.0V			7	μА
I _{IL}	Input LOW	Current	Max.	$V_{IN} = 0.5V^{(3)}$			-1	μA
				$V_{IN} = 0.0V$			-1	1
V _{ID}	Input Leakage Test		0.0	I _{ID} = 1.9μA, All Other Pins Grounded	4.75			V
I _{OZH}	Output Leakage Current		0-5.5V	$V_{OUT} = 2.7V, \overline{OE}_n = 2.0V$			10	μA
I _{OZL}	Output Lea	kage Current	0-5.5V	$V_{OUT} = 0.5V$, $\overline{OE}_n = 2.0V$			-10	μA
I _{OS}	Output Sho	ort-Circuit Current	Max.	$V_{OUT} = 0.0V$	-100		-275	mA
I _{CEX}	Output Higl	h Leakage Current	Max.	$V_{OUT} = V_{CC}$			50	μA
I _{ZZ}	Bus Draina	ge Test	0.0	V _{OUT} = 5.5V, All Others GND			100	μA
I _{CCH}	Power Sup	ply Current	Max.	All Outputs HIGH			50	μA
I _{CCL}	Power Sup	ply Current	Max.	All Outputs LOW			30	mA
I _{CCZ}	Power Sup	ply Current	Max.	$\overline{OE}_n = V_{CC}$, All Others at V_{CC} or Ground			50	μA
I _{CCT}	Additional	Outputs Enabled	Max.	$V_I = V_{CC} - 2.1V$			2.5	mA
	I _{CC} /Input	Outputs 3-STATE		Enable Input V _I = V _{CC} - 2.1V			2.5	mA
	Outputs 3-STATE			Data Input $V_I = V_{CC} - 2.1V$, All Others at V_{CC} or Ground			50	μΑ
I _{CCD}	Dynamic I _{CC} No Load ⁽³⁾		Max.	Outputs OPEN, $\overline{OE}_n = \text{GND}^{(2)}$, One-Bit Toggling, 50% Duty Cycle			0.1	mA/ MHz

Notes:

- 2. For 8-bit toggling, $I_{CCD} < 0.8 mA/MHz$.
- 3. Guaranteed, but not tested.

DC Electrical Characteristics

SOIC package.

Symbol	Parameter	V _{CC}	Conditions $C_L = 50 pF$, $R_L = 500 \Omega$	Min.	Тур.	Max.	Units
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}		$T_A = 25^{\circ}C^{(4)}$		0.5	0.8	V
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}		$T_A = 25^{\circ}C^{(4)}$	-1.3	-0.8		V
V _{OHV}	Minimum HIGH Level Dynamic Output Voltage	5.0	$T_A = 25^{\circ}C^{(6)}$	2.7	3.1		V
V _{IHD}	Minimum HIGH Level Dynamic Input Voltage	5.0	$T_A = 25^{\circ}C^{(5)}$	2.0	1.5		V
V _{ILD}	Maximum LOW Level Dynamic Input Voltage	5.0	$T_A = 25^{\circ}C^{(5)}$		1.1	0.8	V

Notes:

- 4. Max number of outputs defined as (n). n 1 data inputs are driven 0V to 3V. One output at LOW. Guaranteed, but not tested.
- 5. Max number of data inputs (n) switching. n-1 inputs switching 0V to 3V. Input-under-test switching: 3V to threshold (V_{ILD}) , 0V to threshold (V_{IHD}) . Guaranteed, but not tested.
- 6. Max number of outputs defined as (n). n 1 data inputs are driven 0V to 3V. One output HIGH. Guaranteed, but not tested.

AC Electrical Characteristics

SOIC and SSOP package.

		T _A = +25°C, V _{CC} = +5V, C _L = 50pF		$T_A = -55^{\circ}\text{C to } +125^{\circ}\text{C},$ $V_{CC} = 4.5\text{V} - 5.5\text{V},$ $C_L = 50\text{pF}$		$T_A = -40$ °C to +85°C, $V_{CC} = 4.5V-5.5V,$ $C_L = 50$ pF			
Symbol	Parameter	Min.	Тур.	Max.	Min.	Max.	Min.	Max.	Units
t _{PLH}	Propagation Delay	1.0	2.5	3.6	1.0	5.3	1.0	3.6	ns
t _{PHL}	Data to Outputs	1.0	2.3	3.6	1.0	5.0	1.0	3.6	
t _{PZH}	Output Enable Time	1.5	3.5	6.0	0.8	6.5	1.5	6.0	ns
t _{PZL}		1.5	3.6	6.0	1.2	7.9	1.5	6.0	
t _{PHZ}	Output Disable Time	1.7	3.5	5.6	1.2	7.6	1.7	5.6	ns
t _{PLZ}		1.7	3.3	5.6	1.0	7.9	1.7	5.6	

Extended AC Electrical Characteristics

SOIC package.

		$\begin{split} & \textbf{T}_{\textbf{A}} \!$		$\begin{split} T_{A} = -40^{\circ}\text{C to } +85^{\circ}\text{C}, \\ V_{CC} = 4.5\text{V} -5.5\text{V}, \\ C_{L} = 250\text{pF}, \\ 1 \text{ Output} \\ \text{Switching}^{(8)} \end{split}$		$T_{A} = -40^{\circ}\text{C to } +85^{\circ}\text{C},$ $V_{CC} = 4.5\text{V} -5.5\text{V},$ $C_{L} = 250\text{pF},$ 8 Outputs $\text{Switching}^{(9)}$			
Symbol	Parameter	Min.	Тур.	Max.	Min.	Max.	Min.	Max.	Units
f _{TOGGLE}	Max Toggle Frequency		100						MHz
t _{PLH}	Propagation Delay,	1.5		5.0	1.5	6.0	2.5	8.5	ns
t _{PHL}	Data to Outputs	1.5		5.0	1.5	6.0	2.5	8.5	
t _{PZH}	Output Enable Time	1.5		6.5	2.5	7.5	2.5	10.0	ns
t _{PZL}		1.5		6.5	2.5	7.5	2.5	12.0	
t _{PHZ}	Output Disable Time	1.0		5.6	(10)	(1	0)	ns
t _{PLZ}		1.0		5.6					

Notes:

- 7. This specification is guaranteed but not tested. The limits apply to propagation delays for all paths described switching in phase (i.e., all LOW-to-HIGH, HIGH-to-LOW, etc.).
- 8. This specification is guaranteed but not tested. The limits represent propagation delay with 250pF load capacitors in place of the 50pF load capacitors in the standard AC load. This specification pertains to single output switching only.
- 9. This specification is guaranteed but not tested. The limits represent propagation delays for all paths described switching in phase (i.e., all LOW-to-HIGH, HIGH-to-LOW, etc.) with 250pF load capacitors in place of the 50pF load capacitors in the standard AC load.
- 10. The 3-STATE delays are dominated by the RC network (500 Ω , 250pF) on the output and have been excluded from the datasheet.

Skew

		$T_A = -40$ °C to +85°C, $V_{CC} = 4.5V-5.5V$, $C_L = 50$ pF, 8 Outputs Switching ⁽¹³⁾	$T_A = -40$ °C to +85°C, $V_{CC} = 4.5V-5.5V$, $C_L = 250$ pF, 8 Outputs Switching ⁽¹⁴⁾	
Symbol	Parameter	Max.	Max.	Units
t _{OSHL} ⁽¹¹⁾	Pin to Pin Skew, HL Transitions	0.8	1.8	ns
t _{OSLH} ⁽¹¹⁾	Pin to Pin Skew, LH Transitions	0.8	1.8	ns
t _{PS} ⁽¹⁵⁾	Duty Cycle, LH-HL Skew	1.0	2.5	ns
t _{OST} ⁽¹¹⁾	Pin to Pin Skew, LH/HL Transitions	1.0	2.5	ns
t _{PV} ⁽¹²⁾	Device to Device Skew, LH/HL Transitions	1.5	3.0	ns

Notes:

- 11. Skew is defined as the absolute value of the difference between the actual propagation delays for any two separate outputs of the same device. The specification applies to any outputs switching HIGH-to-LOW (t_{OSHL}), LOW-to-HIGH (t_{OSLH}), or any combination switching LOW-to-HIGH and/or HIGH-to-LOW (t_{OST}). The specification is guaranteed but not tested.
- 12. Propagation delay variation for a given set of conditions (i.e., temperature and V_{CC}) from device to device. This specification is guaranteed but not tested.
- 13. This specification is guaranteed but not tested. The limits apply to propagation delays for all paths described switching in phase (i.e., all LOW-to-HIGH, HIGH-to-LOW, etc.)
- 14. These specifications guaranteed but not tested. The limits represent propagation delays with 250pF load capacitors in place of the 50pF load capacitors in the standard AC load.
- 15. This describes the difference between the delay of the LOW-to-HIGH and the HIGH-to-LOW transition on the same pin. It is measured across all the outputs (drivers) on the same chip, the worst (largest delta) number is the guaranteed specification. This specification is guaranteed but not tested.

Capacitance

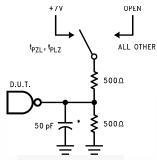
Symbol	Parameter	Conditions T _A = 25°C	Тур.	Units
C _{IN}	Input Capacitance	$V_{CC} = 0V$	5.0	pF
C _{OUT} ⁽¹⁶⁾	Output Capacitance	V _{CC} = 5.0V	9.0	pF

Note:

16. C_{OUT} is measured at frequency f = 1MHz, per MIL-STD-883, Method 3012.



AC Loading



*Includes jig and probe capacitance

Figure 1. Standard AC Test Load

AC Waveforms

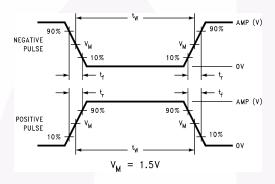


Figure 2. Test Input Signal Levels

Amplitude	Rep. Rate	Rep. Rate t _W		t _f
3.0V	1 MHz	500ns	2.5ns	2.5ns

Figure 3. Test Input Signal Requirements

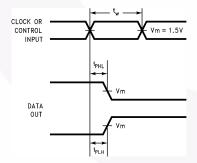


Figure 4. Propagation Delay, Pulse Width Waveforms

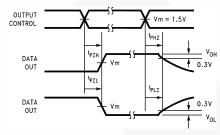


Figure 5. 3-STATE Output HIGH and LOW Enable and Disable Times

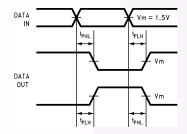


Figure 6. Propagation Delay Waveforms for Inverting and Non-Inverting Functions

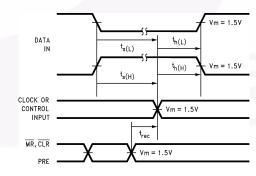


Figure 7. Setup Time, Hold Time and Recovery Time Waveforms

Physical Dimensions 13.00 12.60 11.43 В 9.50 10.65 7.60 10.00 7.40 PIN ONE 0.35 INDICATOR **⊕** 0.25 **M** C B A LAND PATTERN RECOMMENDATION 2.65 MAX SEE DETAIL A 0.33 0.20 0.10 C 0.30 0.10 0.75 0.25 × 45° SEATING PLANE NOTES: UNLESS OTHERWISE SPECIFIED (R0.10) A) THIS PACKAGE CONFORMS TO JEDEC GAGE PLANE MS-013, VARIATION AC, ISSUE E (R0.10) B) ALL DIMENSIONS ARE IN MILLIMETERS. 0.25 C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS. D) CONFORMS TO ASME Y14.5M-1994 0.40 SEATING PLANE E) LANDPATTERN STANDARD: SOIC127P1030X265-20L (1.40)DETAIL A F) DRAWING FILENAME: MKT-M20BREV3

Figure 8. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

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Physical Dimensions (Continued) 12.6±0.10 0.40 TYP -Abo 11 20 12 5.01 TYP 5.3±0.10 9.27 TYP 7.8 -B-10 3.9 (2.13)△ 0.2 C B A ALL LEAD TIPS 10 PIN #1 IDENT. 0.6 TYP 1.27 TYP LAND PATTERN RECOMMENDATION ALL LEAD TIPS SEE DETAIL A △ 0.1 C 2.1 MAX.-1.8±0.1 -C-0.15±0.05 0.15 - 0.250.35-0.51 1.27 TYP ♦ 0.12M C A 7° TYP

DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

GAGE PLANE 0.25 0°-8° TYP 0.60 ± 0.15 SEATING PLANE 1.25 -DETAIL A

M20DREVC

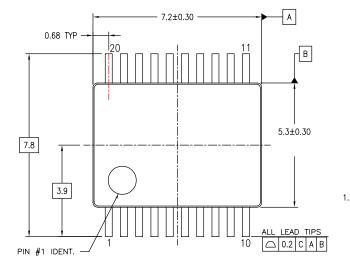
Figure 9. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

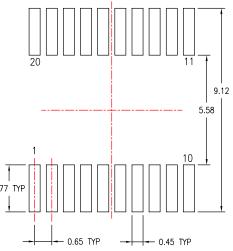
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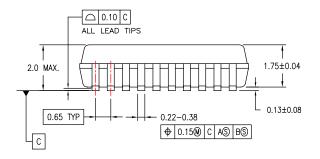
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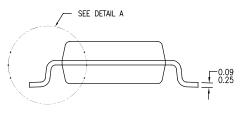
Physical Dimensions (Continued)





LAND PATTERN RECOMMENDATIONS

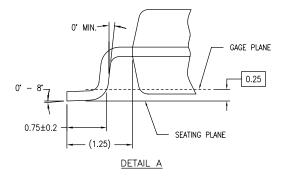




DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-150, VARIATION AE, DATE 1/94.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M 1994.



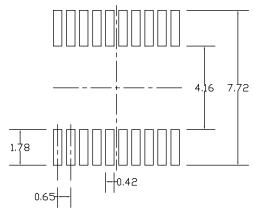
MSA20REVB

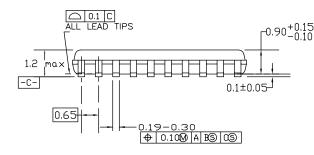
Figure 10. 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide

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Physical Dimensions (Continued) 5.5±0.1 -A--0.20 وحا 6,4 4.4±0.1 -B-3,2 0.2 C B A 0.65 ALL LEAD TIPS PIN #1 IDENT. LAND PATTERN RECOMMENDATION







SEE DETAIL A

DIMENSIONS ARE IN MILLIMETERS

-12.00° R0.09min GAGE PLANE 8 0.25 SEATING PLANE -0.6±0.1 R0.09min

DETAIL A

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MD-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REVD1

Figure 11. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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